DISCRETE SEMICONDUCTORS

DATA SHEET

PDTC124T series NPN resistor-equipped transistors; R1 = 22 k Ω , R2 = open

Product specification Supersedes data of 2004 Apr 06 2004 Aug 13





PDTC124T series

FEATURES

- Built-in bias resistors
- · Simplified circuit design
- Reduction of component count
- Reduced pick and place costs.

APPLICATIONS

- · General purpose switching and amplification
- · Inverter and interface circuits
- · Circuit driver.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V _{CEO}	collector-emitter voltage	_	50	V
Io	output current (DC)	_	100	mA
R1	bias resistor	22	_	kΩ
R2	open	_	_	_

DESCRIPTION

NPN resistor-equipped transistor (see "Simplified outline, symbol and pinning" for package details).

PRODUCT OVERVIEW

TYPE NUMBER	PACE	KAGE	MARKING CODE	DND COMPLEMENT	
I TPE NOWIBER	PHILIPS	PHILIPS EIAJ		PNP COMPLEMENT	
PDTC124TE	SOT416	SC-75	41	PDTA124TE	
PDTC124TEF	SOT490	SC-89	35	PDTA124TEF	
PDTC124TK	SOT346	SC-59	50	PDTA124TK	
PDTC124TM	SOT883	SC-101	DY	PDTA124TM	
PDTC124TS	SOT54 (TO-92)	SC-43	TC124T	PDTA124TS	
PDTC124TT	SOT23	_	*45 ⁽¹⁾	PDTA124TT	
PDTC124TU	SOT323	SC-70	*50 ⁽¹⁾	PDTA124TU	

Note

^{1. * =} p: Made in Hong Kong.

^{* =} t: Made in Malaysia.

^{* =} W: Made in China.

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PDTC124T series

SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	CIMPLIFIED OUTLINE AND CYMPOL		PINNING
TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL	PIN	DESCRIPTION
PDTC124TS		1	base
		2	collector
	1 R1 R1 3 MAM361	3	emitter
PDTC124TE PDTC124TEF PDTC124TK PDTC124TT PDTC124TU	3 1 R1 3 1 Top view MDB270	1 2 3	base emitter collector
PDTC124TM		1	base
		2	emitter
	2 R1 3 Bottom view MHC507	3	collector

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PDTC124T series

ORDERING INFORMATION

TYPE NUMBER		PACKAGE							
I TPE NUMBER	NAME	DESCRIPTION	VERSION						
PDTC124TE	_	plastic surface mounted package; 3 leads	SOT416						
PDTC124TEF	_	plastic surface mounted package; 3 leads	SOT490						
PDTC124TK	_	plastic surface mounted package; 3 leads	SOT346						
PDTC124TM	_	leadless ultra small plastic package; 3 solder lands; body $1.0 \times 0.6 \times 0.5 \text{ mm}$	SOT883						
PDTC124TS	_	plastic single-ended leaded (through hole) package; 3 leads	SOT54						
PDTC124TT	_	plastic surface mounted package; 3 leads	SOT23						
PDTC124TU	1	plastic surface mounted package; 3 leads	SOT323						

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	50	V
V _{CEO}	collector-emitter voltage	open base	_	50	V
V _{EBO}	emitter-base voltage	open collector	_	5	V
Io	output current (DC)		_	100	mA
I _{CM}	peak collector current		_	100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C			
	SOT54	note 1	_	500	mW
	SOT23	note 1	_	250	mW
	SOT346	note 1	_	250	mW
	SOT323	note 1	_	200	mW
	SOT490	notes 1 and 2	_	250	mW
	SOT883	notes 2 and 3	_	250	mW
	SOT416	note 1	_	150	mW
T _{stg} storage temperature			-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 μm copper strip line.

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PDTC124T series

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	in free air		
	SOT54	note 1	250	K/W
	SOT23	note 1	500	K/W
	SOT346	note 1	500	K/W
	SOT323	note 1	625	K/W
	SOT490	notes 1 and 2	500	K/W
	SOT883	notes 2 and 3	500	K/W
	SOT416	note 1	833	K/W

Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 μm copper strip line.

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	V _{CB} = 50 V; I _E = 0 A	_	_	100	nA
I _{CEO}	collector-emitter cut-off current	$V_{CE} = 30 \text{ V}; I_{B} = 0 \text{ A}$	_	_	1	μΑ
		$V_{CE} = 30 \text{ V}; I_{B} = 0 \text{ A}; T_{j} = 150 ^{\circ}\text{C}$	_	_	50	μΑ
I _{EBO}	emitter-base cut-off current	V _{EB} = 5 V; I _C = 0 A	_	_	100	nA
h _{FE}	DC current gain	V _{CE} = 5 V; I _C = 1 mA	100	_	_	
V _{CEsat}	collector-emitter saturation voltage	$I_C = 10 \text{ mA}; I_B = 0.5 \text{ mA}$	_	_	150	mV
R1	input resistor		15.4	22	28.6	kΩ
C _c	collector capacitance	$I_E = I_e = 0 \text{ A}; V_{CB} = 10 \text{ V};$ f = 1 MHz	_	_	2.5	pF

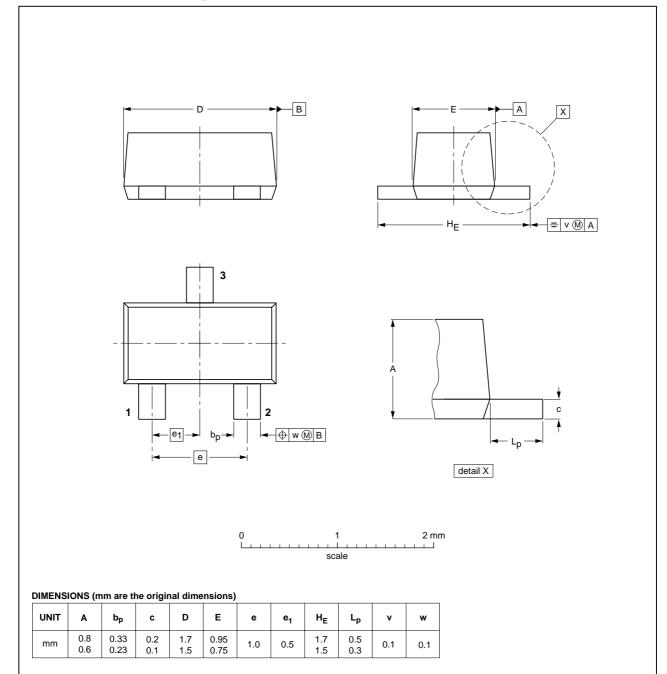
NPN resistor-equipped transistors; R1 = 22 k Ω , R2 = open

PDTC124T series

PACKAGE OUTLINES

Plastic surface mounted package; 3 leads

SOT490

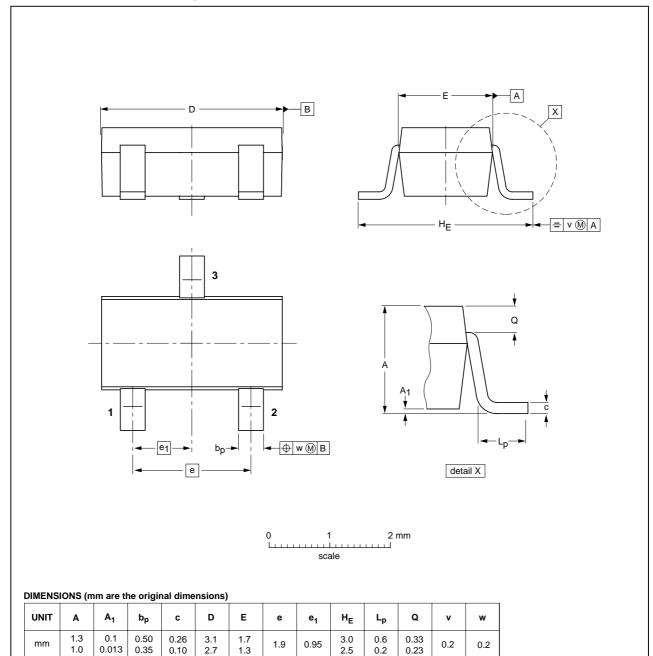


	REFER	ENCES		EUROPEAN	ISSUE DATE	
IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
		SC-89			98-10-23	
	IEC			IEC JEDEC EIAJ	IEC JEDEC EIAJ PROJECTION	

PDTC124T series

Plastic surface mounted package; 3 leads

SOT346



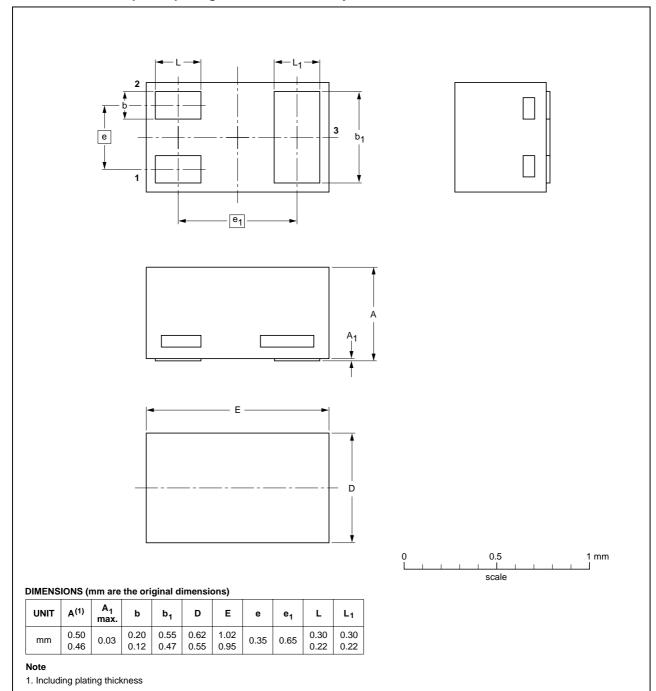
OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
SOT346		TO-236	SC-59		98-07-17	

NPN resistor-equipped transistors; R1 = 22 k Ω , R2 = open

PDTC124T series

Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm

SOT883



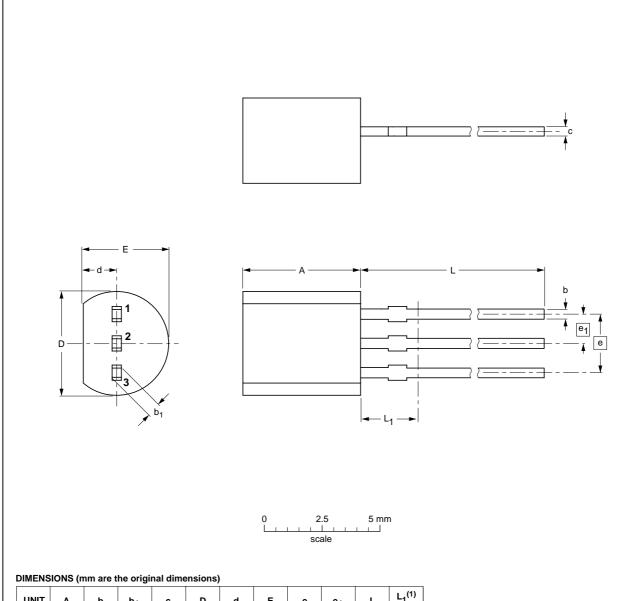
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION		
SOT883			SC-101		03-02-05 03-04-03	

NPN resistor-equipped transistors; R1 = 22 k Ω , R2 = open

PDTC124T series

Plastic single-ended leaded (through hole) package; 3 leads

SOT54



UNIT	A	b	b ₁	С	D	d	E	е	e ₁	L	L ₁ ⁽¹⁾ max.	
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5	

Note

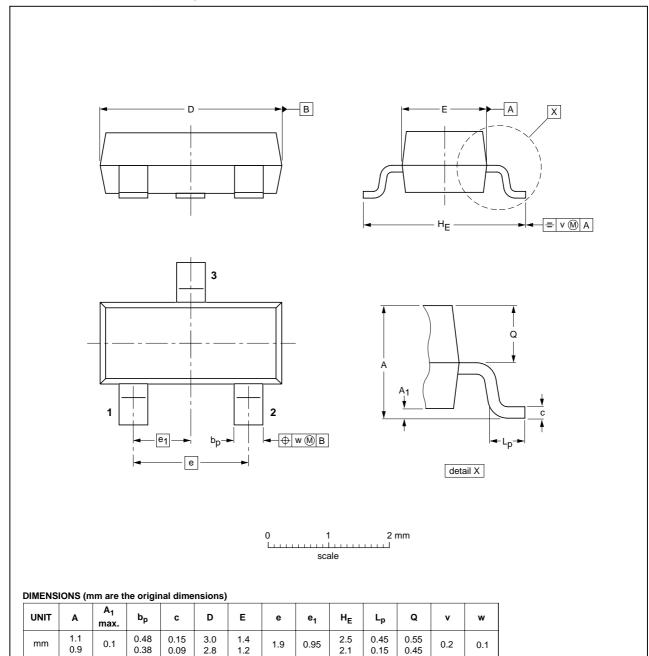
1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE		REFER	FERENCES EUROPEAN ISSI		ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT54		TO-92	SC-43A			97-02-28 04-06-28	

PDTC124T series

Plastic surface mounted package; 3 leads

SOT23

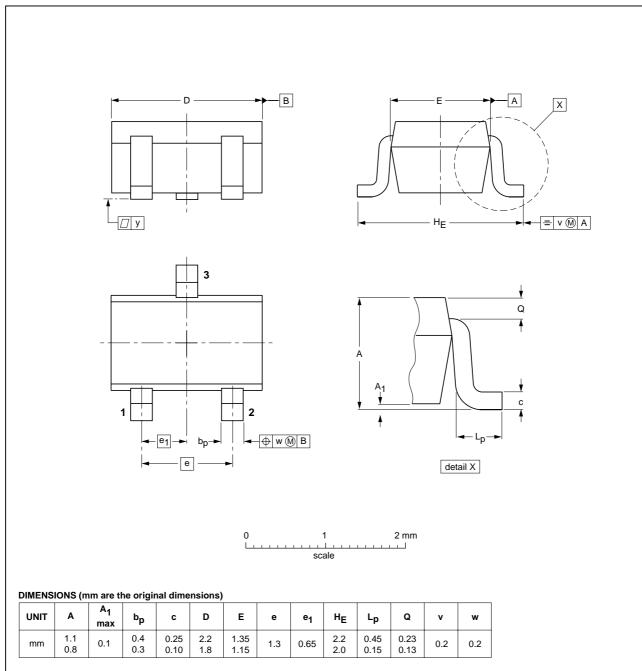


OUTLINE VERSION	REFERENCES			EUROPEAN	ISSUE DATE	
	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT23		TO-236AB				-97-02-28- 99-09-13

PDTC124T series

Plastic surface mounted package; 3 leads

SOT323

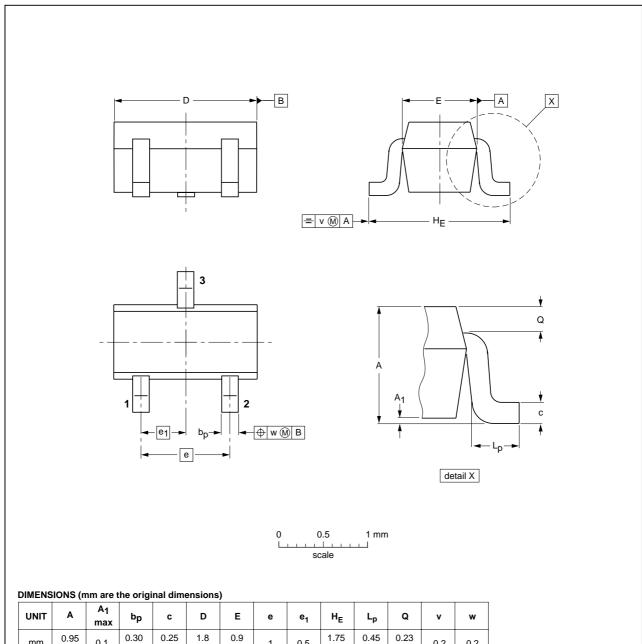


REFERENCES			EUROPEAN	ISSUE DATE	
IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
		SC-70			97-02-28
	IEC		IEC JEDEC EIAJ	IEC JEDEC EIAJ	IEC JEDEC EIAJ PROJECTION

PDTC124T series

Plastic surface mounted package; 3 leads

SOT416



OUTLINE VERSION	REFERENCES				EUROPEAN	ISSUE DATE
	IEC	JEDEC	EIAJ		PROJECTION	1350E DATE
SOT416			SC-75			97-02-28

0.2

0.2

0.5

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0.10

0.1

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PDTC124T series

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Notes

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- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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